



Docket No.: 20135-00311-US
(PATENT)

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
William E. Bernier, et al.

Conf. No.: 1044

Application No.: 09/687,524

Group Art Unit: 1725

Filed: October 12, 2000

Examiner: Jonathan J. Johnson

For: **SOLDER PROTECTIVE COATING AND
FLUXLESS JOINING OF FLIP CHIP DEVICES
ON LAMINATES WITH PLATED SOLDER**

SUBMISSION OF FORMAL DRAWINGS

Commissioner for Patents
Washington, DC 20231

Dear Sir:

In accordance with the Notice of Allowability mailed January 27, 2003, Applicants submit herewith 1 sheets of formal drawings of Figs. 1A-1D.

Dated: February 13, 2003

Respectfully submitted,

By 
Burton A. Amernick

Registration No.: 24,852
CONNOLLY BOVE LODGE & HUTZ, LLP
1990 M Street, N.W., Suite 800
Washington, DC 20036-3425
(202) 331-7111
(202) 293-6229 (Fax)
Attorneys for Applicant



Sheet 1/1
William E. Bernier et al.
END-00-0034US1 (LRF)

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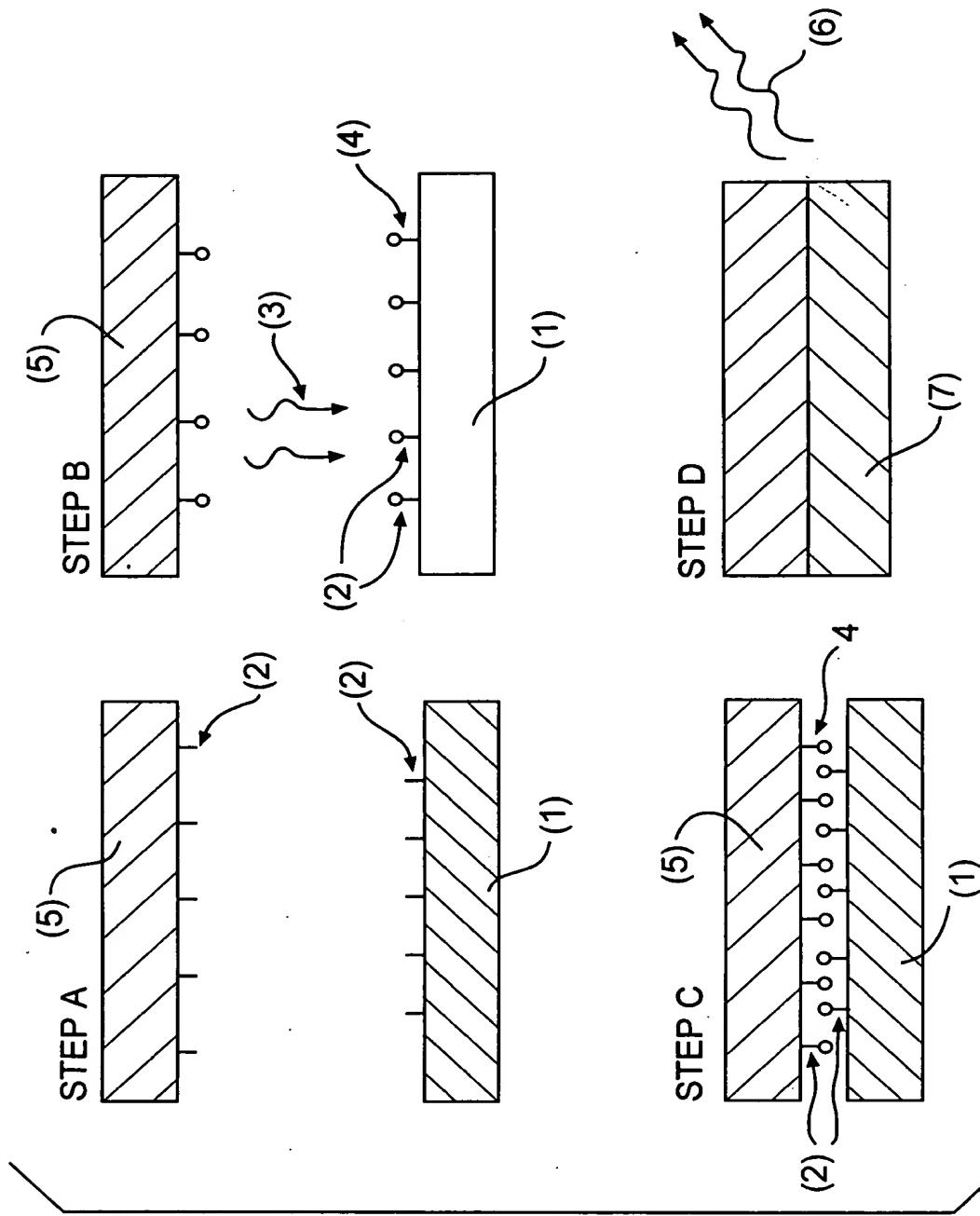


FIG. 1